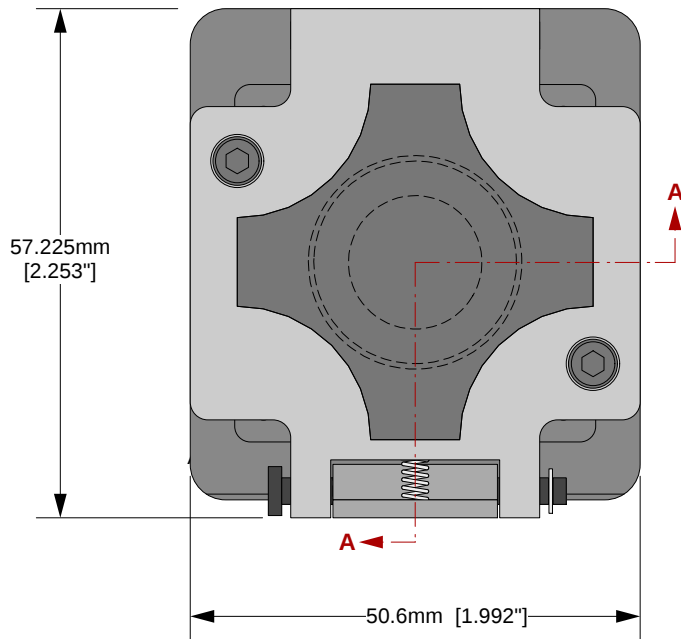
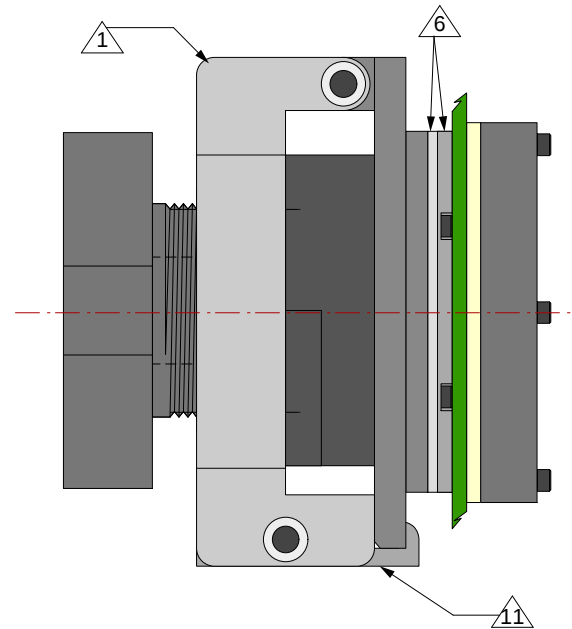




Top View



Features

Directly mounts to target PCB (needs tooling holes) with hardware

Minimum real estate required

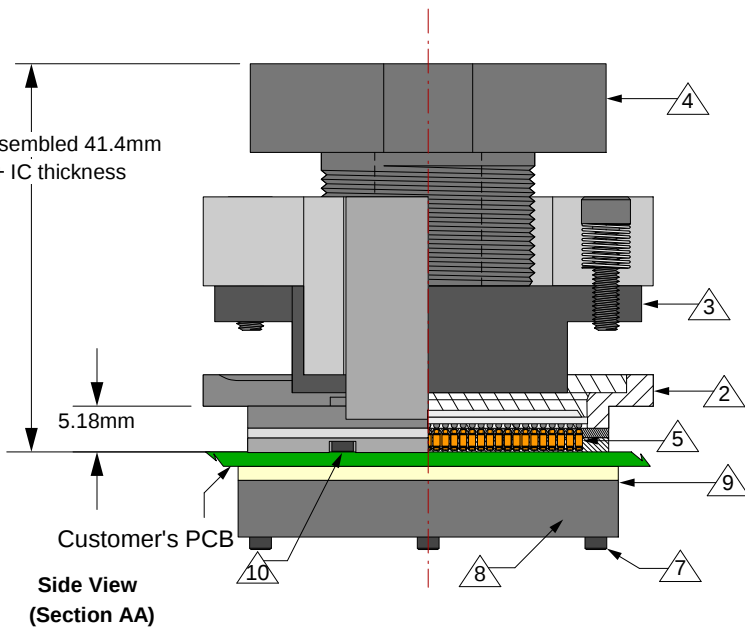
Compression plate distributes forces evenly

Clamshell lid

Materials:

- 1 Clam Shell Lid: Black anodized Aluminum.
Height = 20 mm.
- 2 Socket Base: Black anodized Aluminum.
Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum.
Thickness = 12 mm.
- 4 Compression Screw: Clear anodized Aluminum.
Height = 27 mm
- 5 Pogo Pin:
Plungers - Hardened Steel/ Gold plated
Barrel - Copper Alloy/ Gold plated
Spring - Stainless Steel/ Gold wire
- 6 Pogo Pin Guides: Ceramic Filled Peek.
- 7 Socket Base Screw: Socket Head Cap Screw,
2-56 Thread, 5/8" long.
- 8 Backing Plate: Black anodized Aluminum.
- 9 Insulation Plate: Ultem, 1.59mm thick.
- 10 Pogo Pin Guide Screw: Pan head phillips, 18-8
SS, 0-80 thread, 3/16" long.
- 11 Latch: Black anodized Aluminum.

All Tolerances: $\pm 0.125\text{mm}$ (unless stated otherwise). Materials and specifications are subject to change without notice.



Side View
(Section AA)

SS-BGA1156A-02 Drawing

Status: Released

Scale: -

Rev: A



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Drawing: E Smolentseva

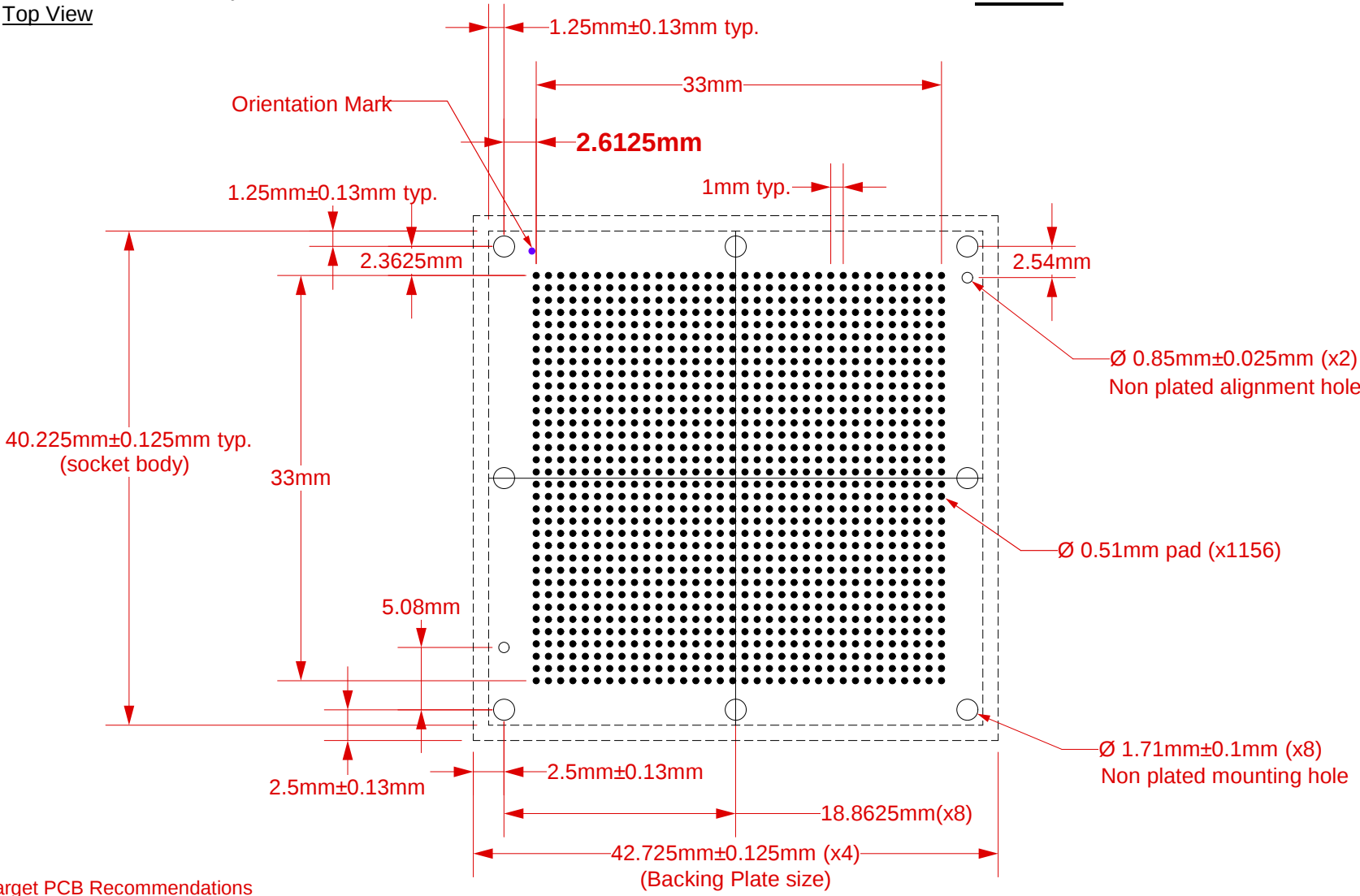
Date: 02/27/09

File: SS-BGA1156A-02 Dwg.mcd

Modified: 04/22/09

Note: BGA pattern is shifted by 0.25mm to the right with respect to the mounting holes.

Recommended PCB Layout
Top View



Target PCB Recommendations

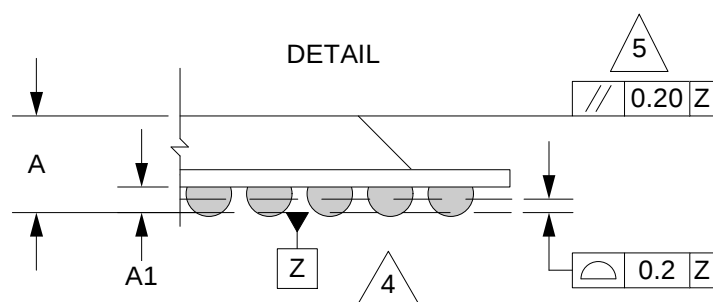
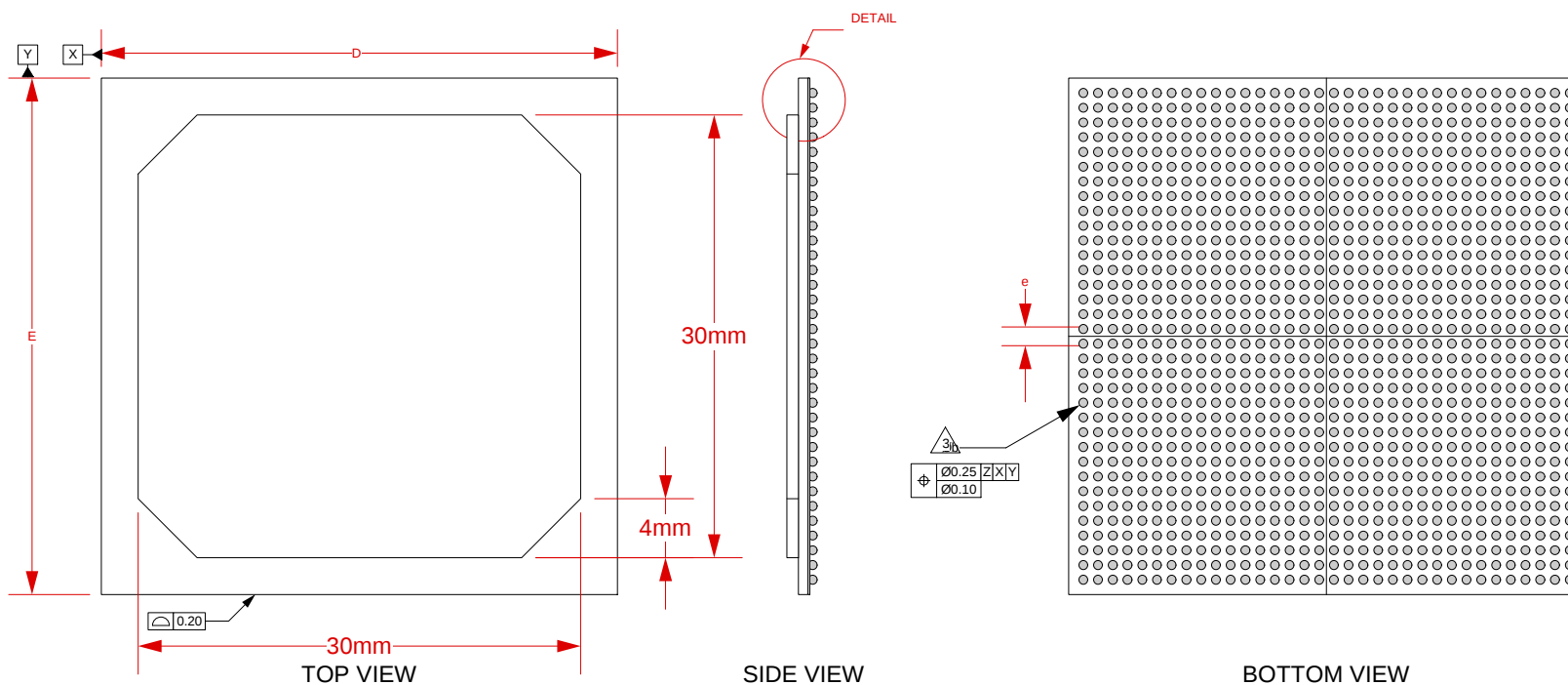
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

NOTE: Steel backing plate may be required based on end user's application

Recommended PCB Layout Tolerances: ±0.025mm [±0.001"] unless stated otherwise.

SS-BGA1156A-02 Drawing		Status: Released	Scale: -	Rev: A
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		File: SS-BGA1156A-02 Dwg.mcd		Modified: 04/22/09

Compatible BGA Spec

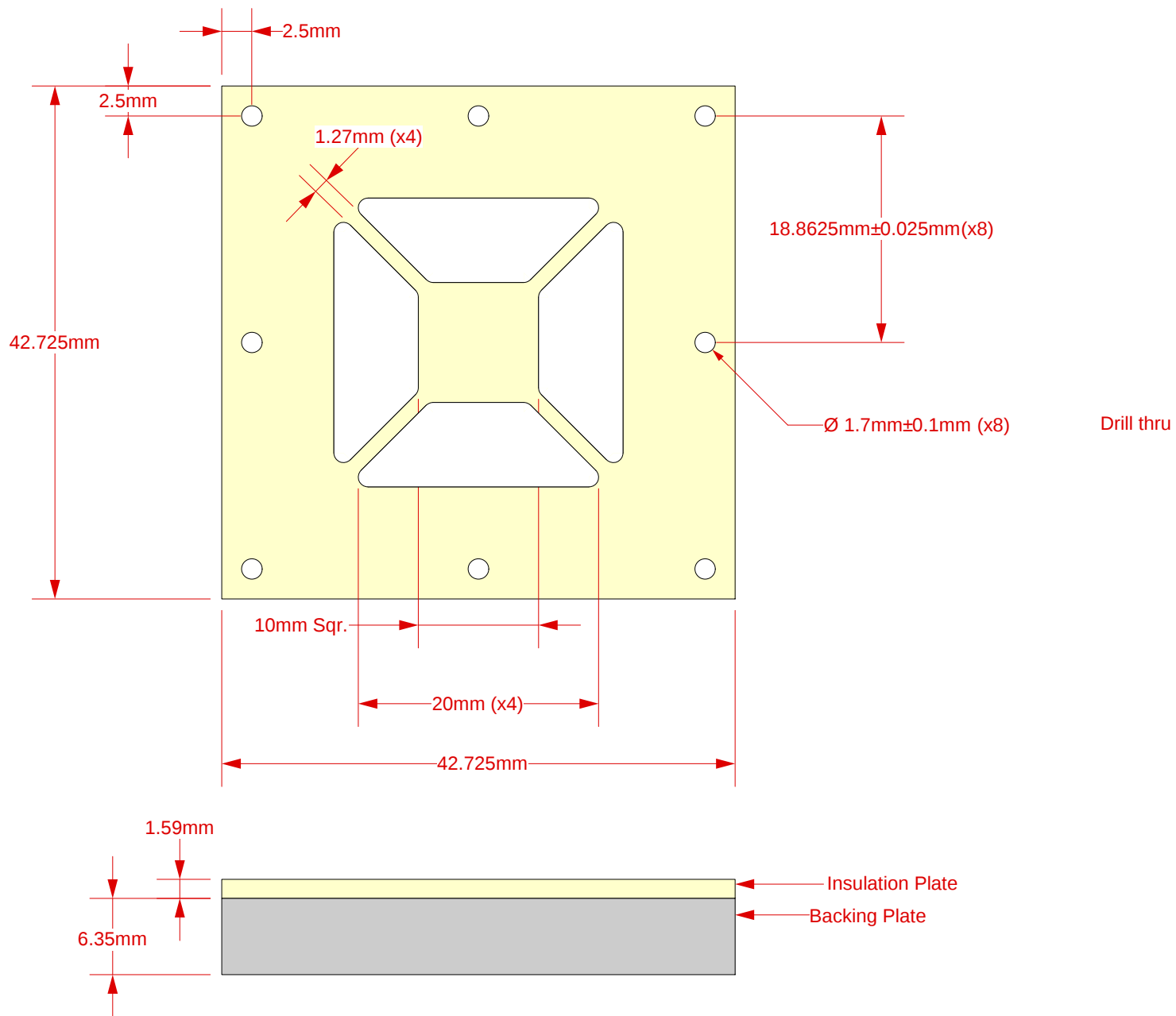


1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.23
A1	0.4	0.6
b	0.5	0.7
D	35.0 BSC	
E	35.0 BSC	
e	1.00 BSC	

Array 34x34

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	Drawing: E Smolentseva		Date: 02/27/09		
	File: SS-BGA1156A-02Dwg.mcd		Modified: 04/22/09		



Side View

Description: Insulation Plate and Backing Plate

SS-BGA1156A-02 Drawing		Status: Released	Scale: -	Rev: A
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	File: SS-BGA1156A-02 Dwg.mcd		Modified: 04/22/09	

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All dimensions are in mm.
All tolerances are $\pm 0.125\text{mm}$.
(Unless stated otherwise)